

ABSTRACT

A method for cutting apart a glass substrate is provided whereby scribing of the glass substrate is possible without being affected by the presence or thickness of a deposited film formed thereon and without scratching the deposited film. To treat a glass substrate (1) having a deposited film (1a), such as a thin film or resin film, formed on one surface thereof, there are provided a shaving means (202), which is a blade that removes strip-shaped portions of the deposited film (1a) to expose strip-shaped regions on the glass substrate (1), and a wheel cutter (14a) that forms scribed lines along the strip-shaped regions exposed on the glass substrate (1). The glass substrate (1) is cut apart along the scribed lines.